

General Description:

The JS3N10AD3D uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is DFN3.3*3.3, which accords with the RoHS standard.

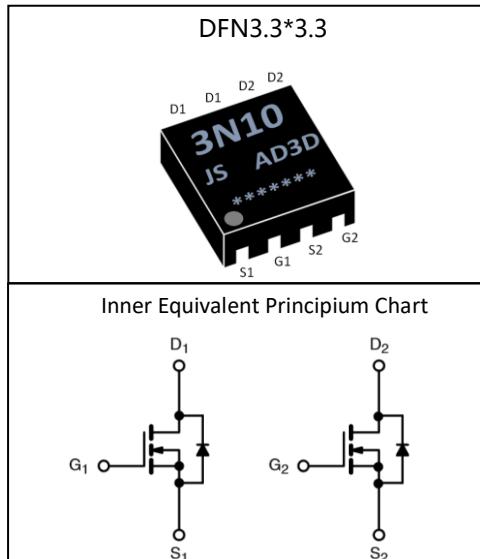
V_{DSS}	100	V
I_D	3	A
P_D	1.5	W
$R_{DS(ON)} \text{ TYPE}$	0.155	Ω

Features:

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications:

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply


Package Marking and Ordering Information:

Device Marking	Device	Device Package	Quantity
JS3N10AD3D	JS3N10AD3D	DFN3.3*3.3	5000 units

Absolute Maximum Ratings (TA = 25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	100	V
I_D	Continuous Drain Current	3.0	A
	Continuous Drain Current $T_C = 100^\circ\text{C}$	1.7	A
I_{DM}^{a1}	Pulsed Drain Current	12	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}^{a2}	Single Pulse Avalanche Energy	50	mJ
E_{AR}^{a1}	Avalanche Energy, Repetitive	1.25	mJ
I_{AR}^{a1}	Avalanche Current	1.8	A
dv/dt^{a3}	Peak Diode Recovery dv/dt	5.0	V/ns
P_D	Power Dissipation	1.5	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 175	°C
T_L	Maximum Temperature for Soldering	300	°C

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu\text{A}$	100	--	--	V
$\Delta V_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	$I_D=250\mu\text{A}$, Reference 25°C	--	0.1	--	$^\circ\text{C}$
I_{DSS}	Drain to Source Leakage Current	$V_{DS} = 100V, V_{GS} = 0V, T_a = 25^\circ\text{C}$	--	--	1	μA
		$V_{DS} = 80V, V_{GS} = 0V, T_a = 125^\circ\text{C}$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS} = +20V$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS} = -20V$	--	--	-100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=3.0\text{A}$	--	155	185	$\text{m}\Omega$
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=6V, I_D=2.5\text{A}$	--	175	210	$\text{m}\Omega$
$V_{GS(\text{TH})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	--	3.0	V
Pulse width $t_p \leq 380\mu\text{s}, \delta \leq 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D = 3\text{A}$	4	--	--	S
C_{iss}	Input Capacitance	$V_{GS} = 0V$	--	510	--	pF
C_{oss}	Output Capacitance	$V_{DS} = 50V$	--	18	--	
C_{rss}	Reverse Transfer Capacitance	f = 1.0MHz	--	15	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D = 3.0\text{A}$	--	7	--	ns
t_r	Rise Time		--	5	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	20	--	
t_f	Fall Time		--	5	--	
Q_g	Total Gate Charge	$I_D = 3\text{A}$	--	15	--	nC
Q_{gs}	Gate to Source Charge		--	1.6	--	
Q_{gd}	Gate to Drain ("Miller") Charge		--	2.5	--	

Source-Drain Diode Characteristics		Test Conditions	Rating			Units
Symbol	Parameter		Min.	Typ.	Max.	
I _S	Continuous Source Current (Body Diode)		--	--	3	A
I _{SM}	Maximum Pulsed Current (Body Diode)		--	--	12	A
V _{SD}	Diode Forward Voltage	I _S =3.0A, V _{GS} =0V	--	--	1.5	V
t _{rr}	Reverse Recovery Time	I _S =3.0A, T _j = 25°	--	50	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt=100A/us, V _{GS} =0V	--	180	--	nC
Pulse width tp≤380μs, δ≤2%						

Thermal Characteristics

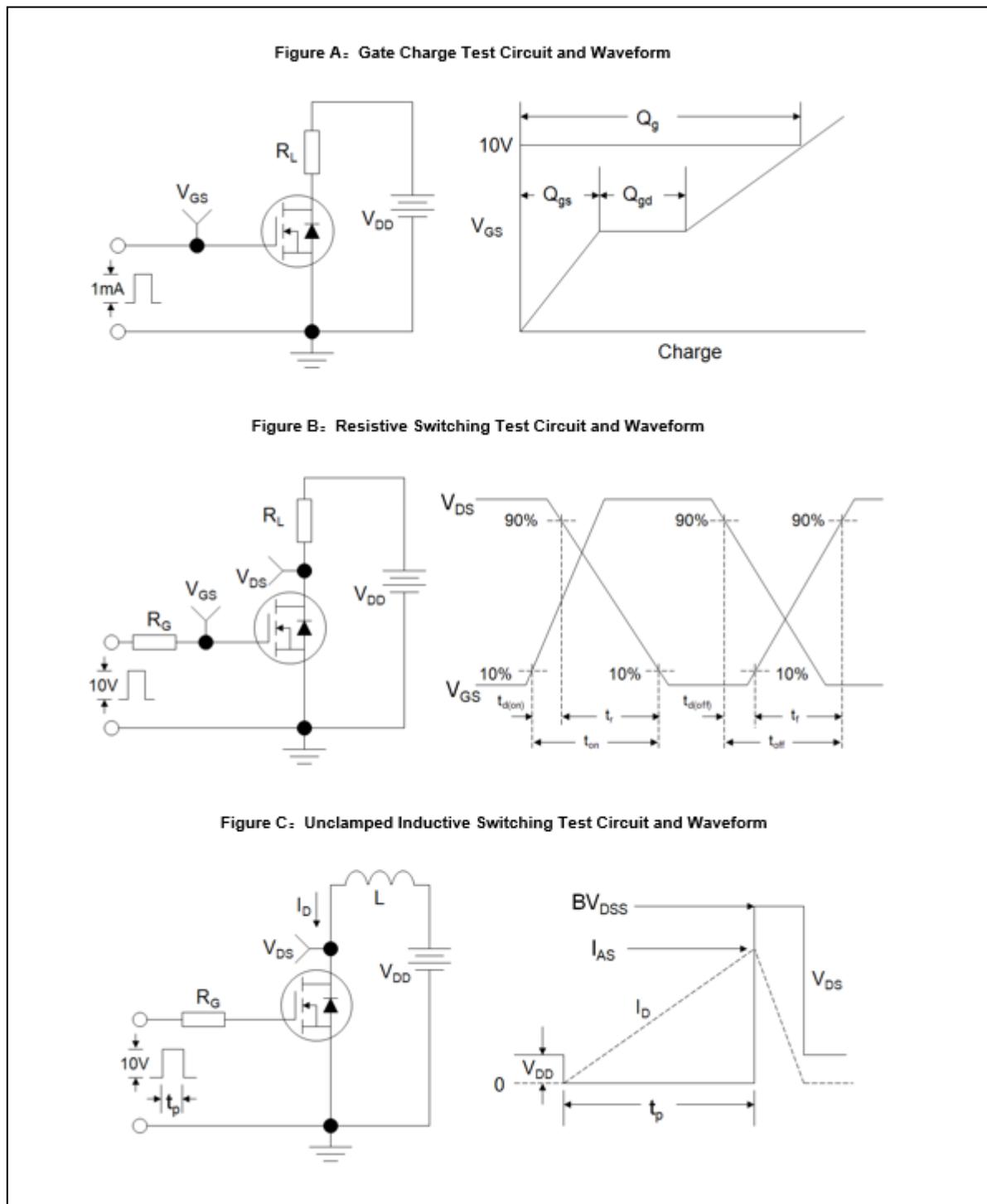
Symbol	Parameter	Typ.	Units
R _{θJC}	Junction-to-Case	4.5	°C/W
R _{θJA}	Junction-to-Ambient	83	°C/W

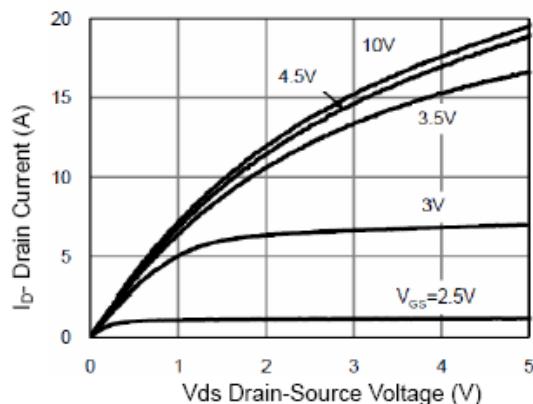
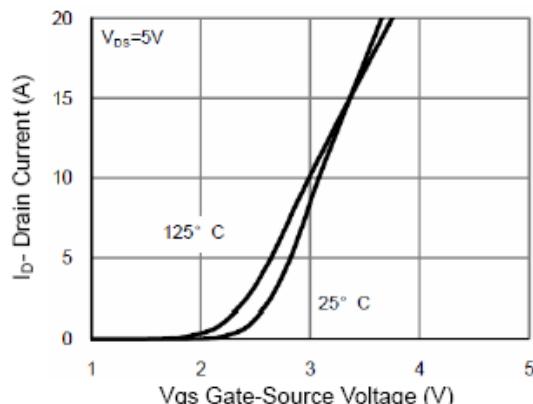
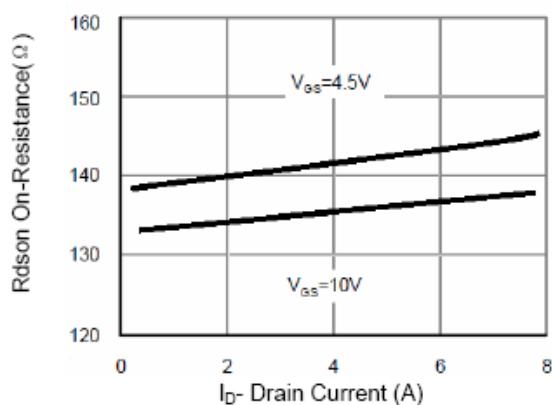
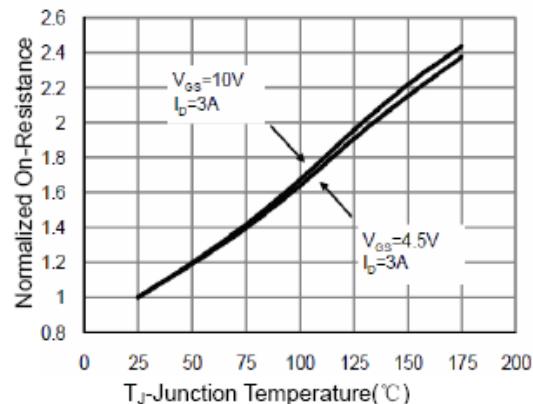
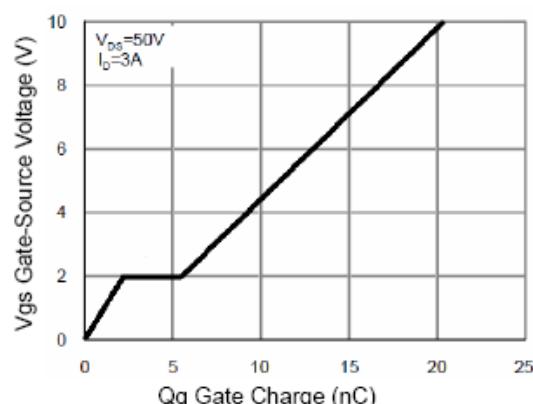
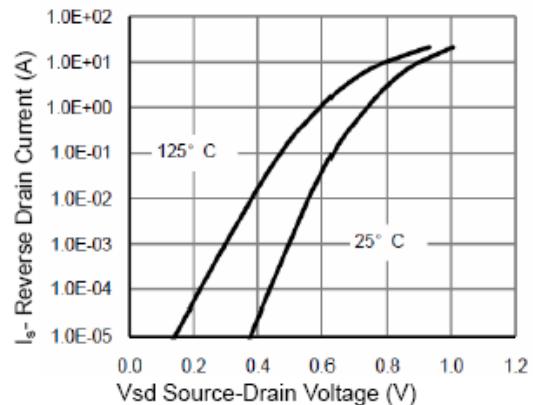
^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

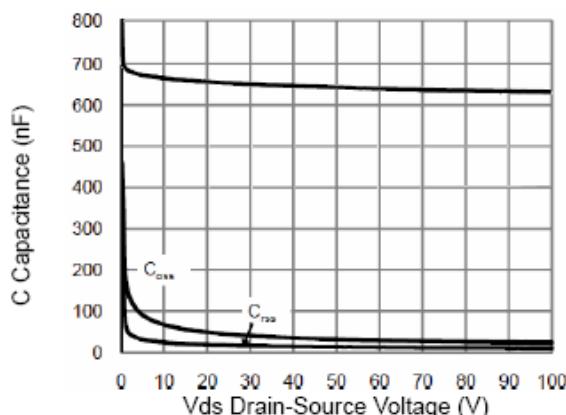
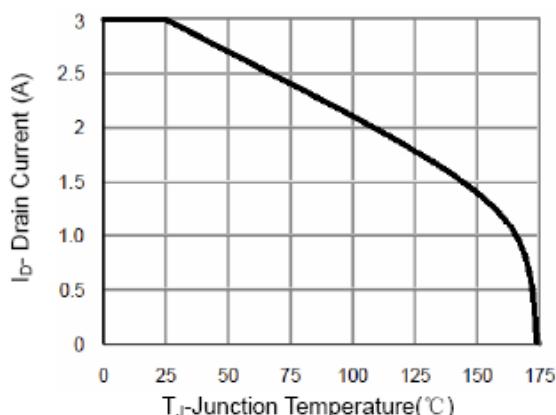
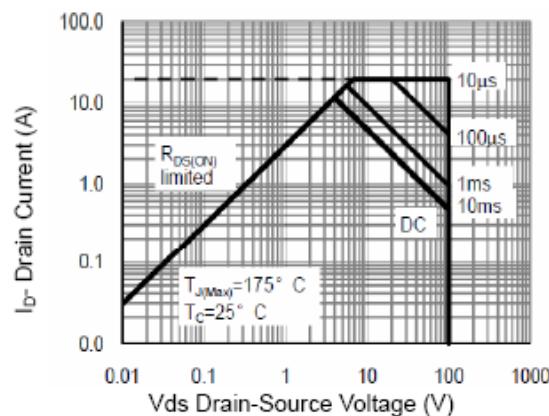
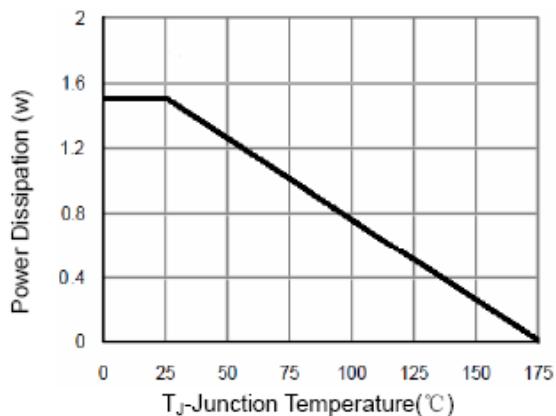
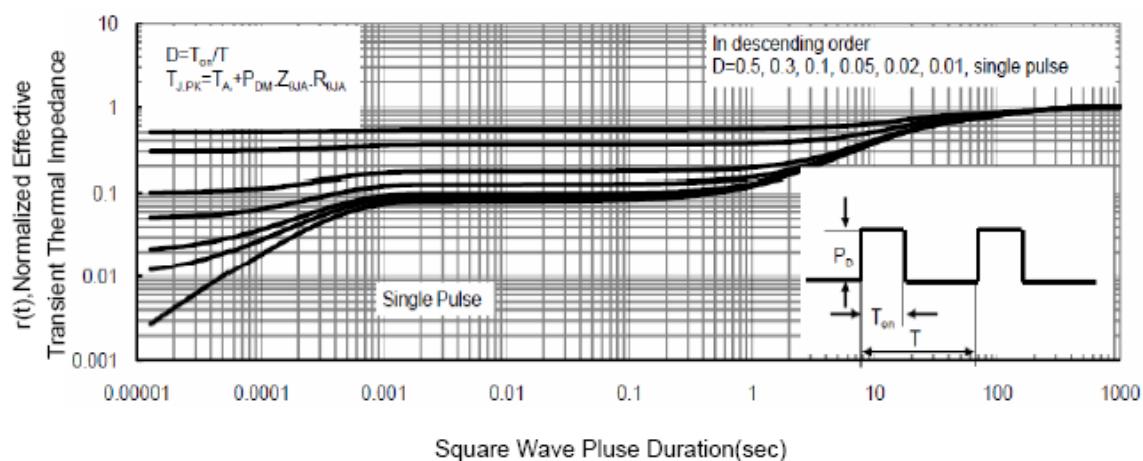
^{a2}: L=10.0mH, I_D=0.5A, Start T_j=25°C

^{a3}: I_{SD} =3A,di/dt ≤100A/us, V_{DD}≤BV_{DS}, Start T_j=25°C

Test Circuit and Waveform



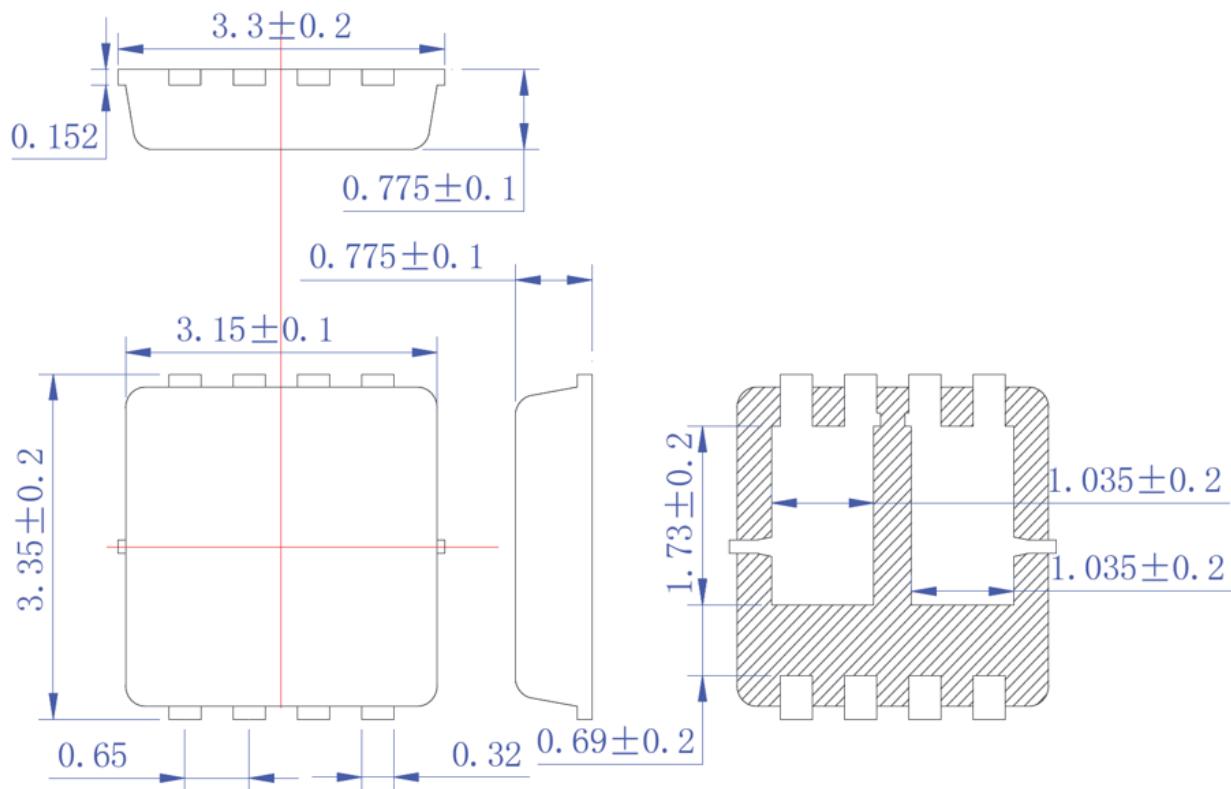
Typical Electrical and Thermal Characteristics (Curves)

Figure 1 Output Characteristics

Figure 2 Transfer Characteristics

Figure 3 Rdson- Drain Current

Figure 4 Rdson-JunctionTemperature

Figure 5 Gate Charge

Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 BV_{DSS} vs Junction Temperature

Figure 8 Safe Operation Area

Figure 10 Power De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance

Marking Information

JS	XX	XX	XX	-	XX
					Package Type
					AD3 DFN3*3
					D Dual Chips
					Second Functional Option
					Drain to Source Breakdown Voltage
					N-channel or P-channel
					First Functional Option
					Continuous Drain Current
					Company Prefix
					JS Prefix

		Part	NO.	
●	Y	M	W	SN
Part NO.	JS3N10AD3D			
●	Pin 1 Indicator			
Lot NO.	Y: Year; M: Month; W: Week; SN: Pipeline Code			

Package Information

Revision History

Revision	Date	Descriptions
REV.1.2	Dec., 2018	"Add Marking Information and Package Information" Update
REV.1.1	Aug., 2018	"Typical Performance Characteristics" Update
REV.1.0	July, 2017	Initial Version